

October 3-5, 2016

**International Workshop on Power Supply On Chip
(PwrSoC 2016)**

The Panasonic logo is displayed in white text on a blue rectangular background in the top right corner of the slide.

Monolithic integration of GaN power transistors integrated with gate drivers

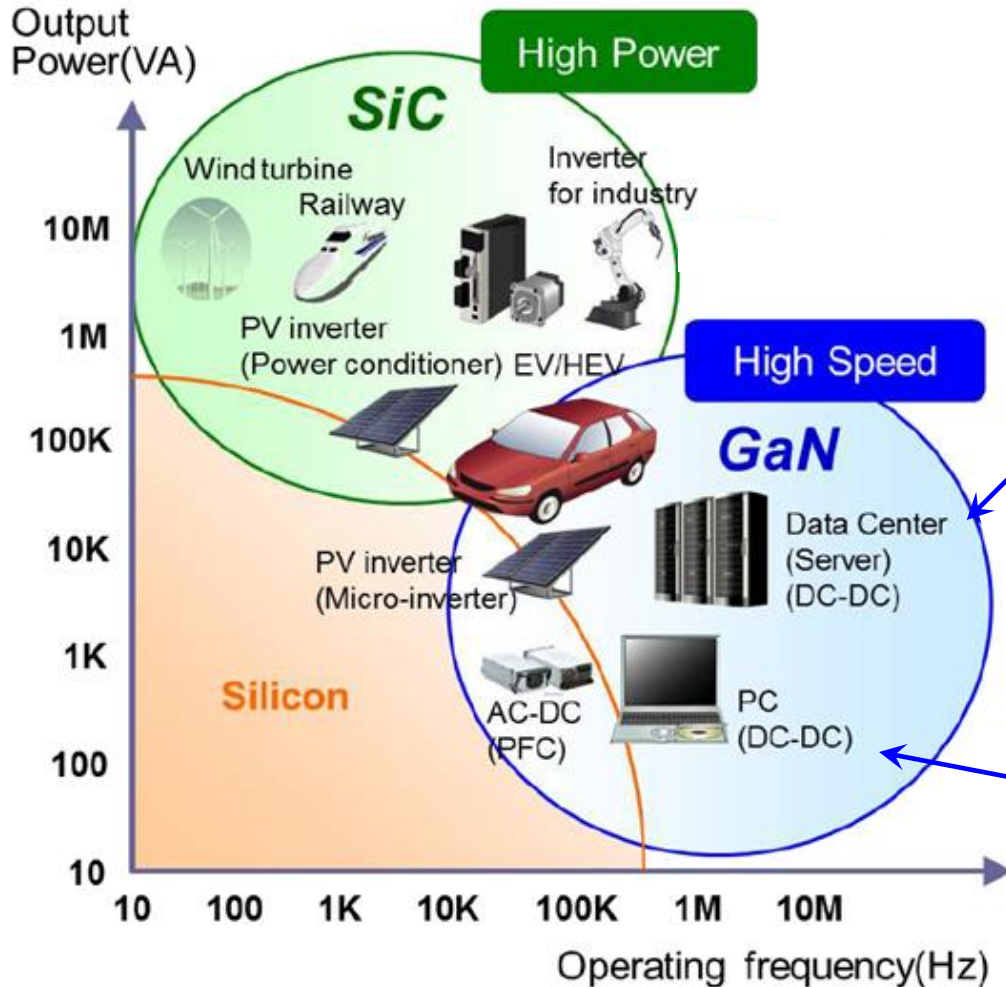
October 4, 2016

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Panasonic Corporation**

Potential Application for WBG semiconductors

- GaN power transistors are suited for high-frequency applications.



Production
Normally-off
GaN Gate Injection Transistor
(GaN-GIT)

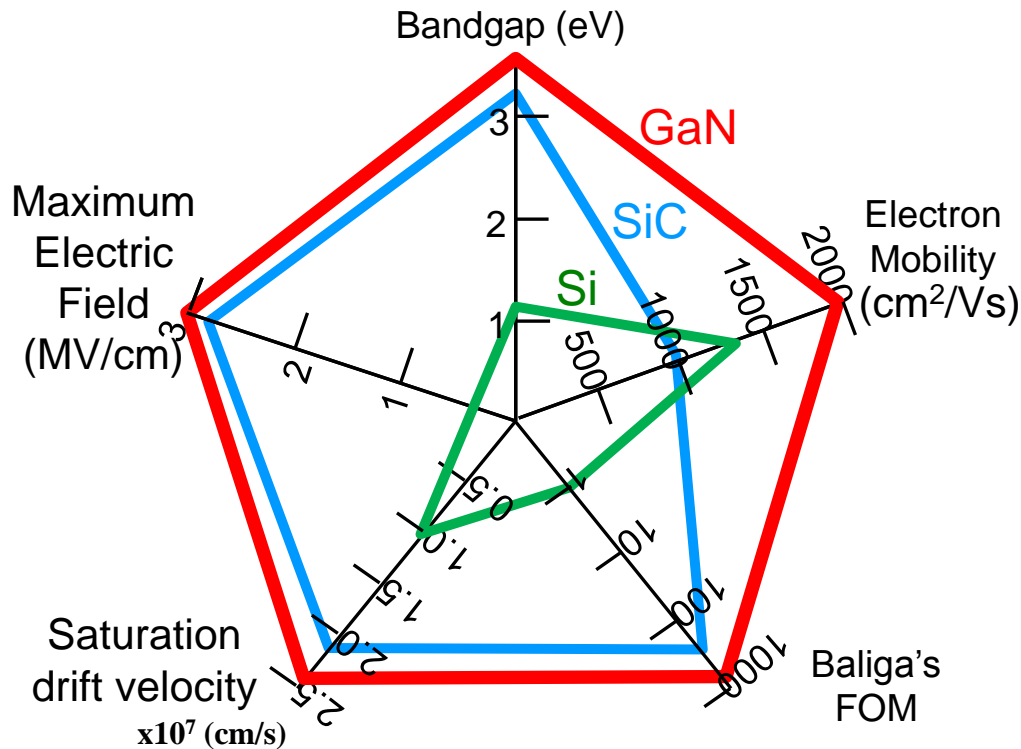
600V/15A TO-220 600V/15A SMD

Proto-type
30V normally-off
GaN-GITs
(developed in 2014)

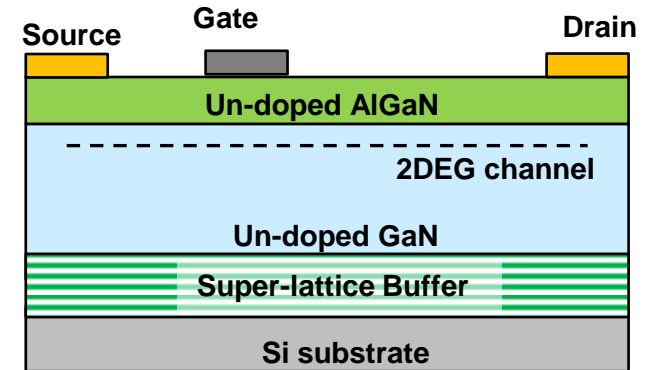
Advantages of GaN for Power device

- GaN inherently has superior material properties for Power switching device
- Unique feature of GaN is 2-Dimensional Electron Gas(2DEG) which serves both high electron density and high electron mobility

Comparison of material properties



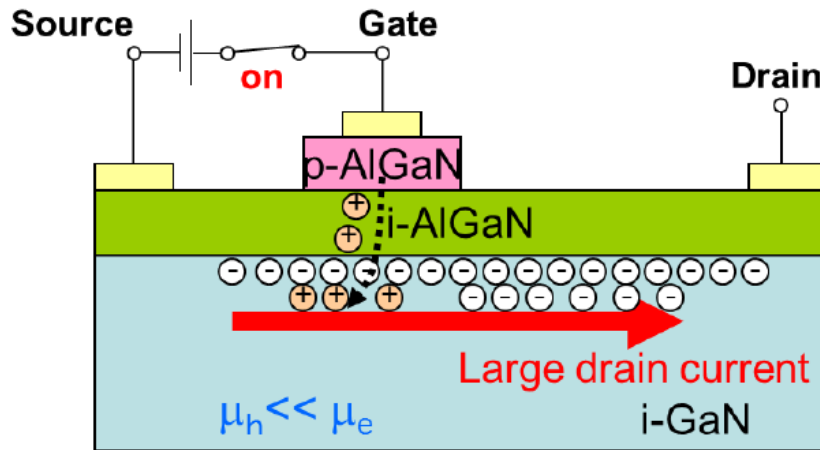
AlGaN/GaN Hetero-junction FET



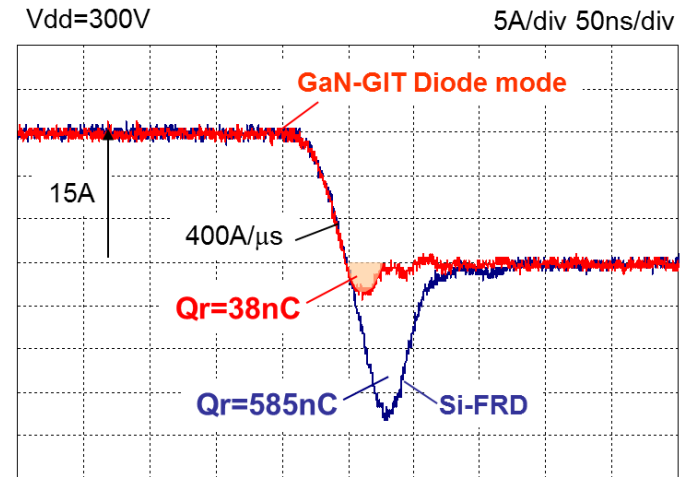
- High sheet carrier density induced by polarization effects at the AlGaN/GaN hetero-interface without any doping
- GaN-FET can be fabricated on cost-effective Si-substrates
- Normally-on operation

Normally-off GaN Gate Injection Transistors - GIT -

Gate Injection Transistor (GIT)



Recovery characteristics



Normally-off operation

$V_g=0V$: p-AlGaN lifts up the potential at the channel.

$V_g > V_f$: Hole injection \rightarrow Electron generation \rightarrow Large Drain current

Very low RonQg

RonQg of 600V GIT is 0.7 Ω nC which is 1/13 of that of the latest SJ-MOSFET.

Good Recovery characteristics

GIT can be operated as a free-wheeling diode with very small charging current.

Power supply

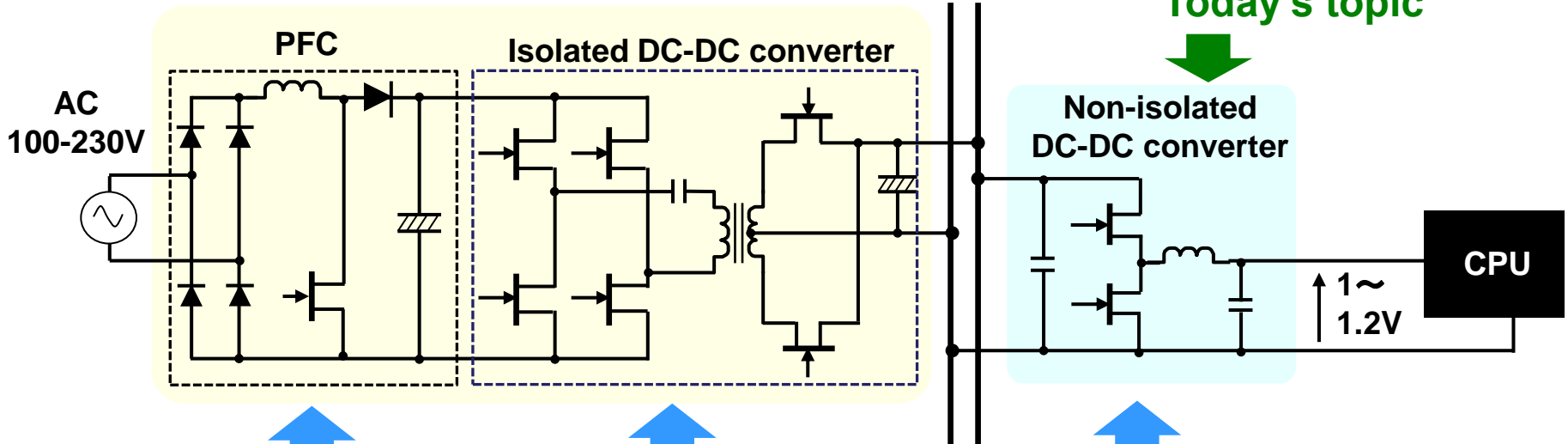
- Power converter have progressed with overcoming design trade-off among power density and efficiency, cost.
- To make more advanced, GaN-FETs have been actively investigated.

GaN power devices used in Power supply

AC-DC Power Supply

DC12V Bus

Today's topic



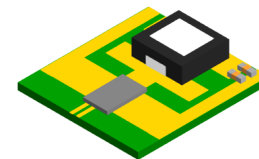
Totem-pole PFC using GfTs reported by Panasonic on PCIM2014



1MHz resonant converter using 600V normally-off GaNs reported by Fraunhofer ISE on ECSCRM2012



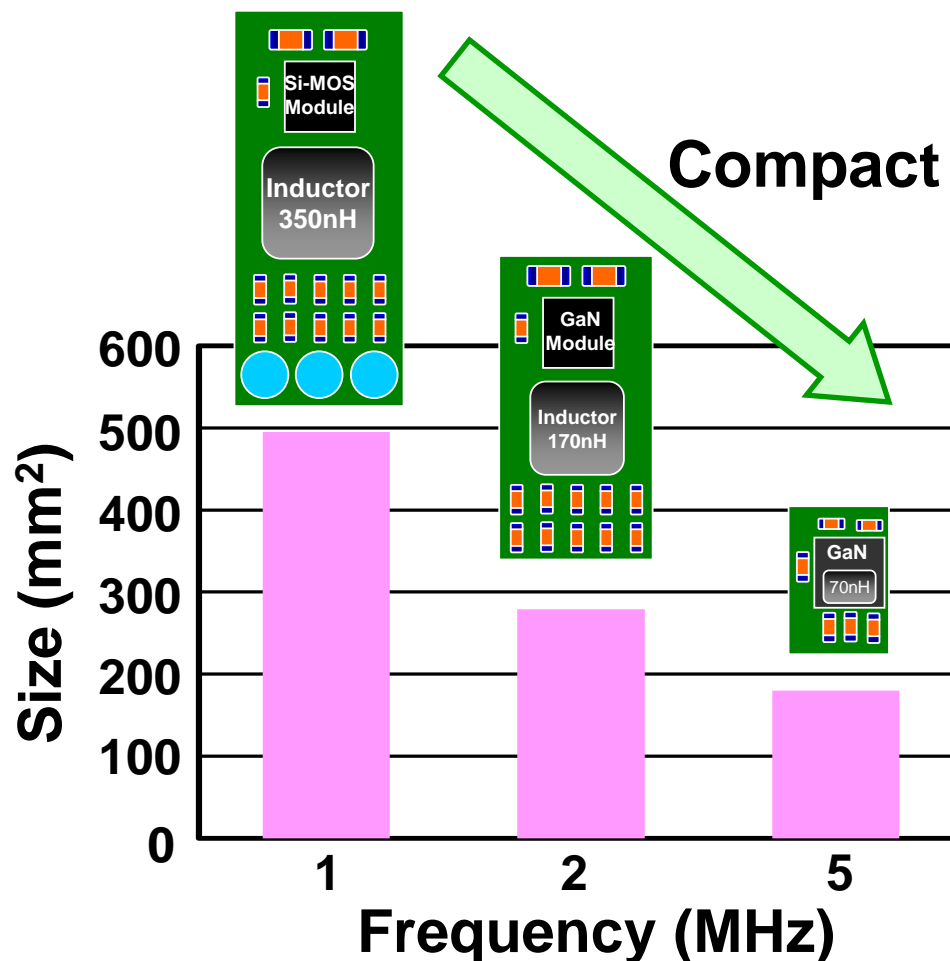
- 5MHz/50A GaN POL converter reported on PCIM2014
- GaN POL power IC integrated with gate drivers reported on ISPSD14



For smaller POL converter

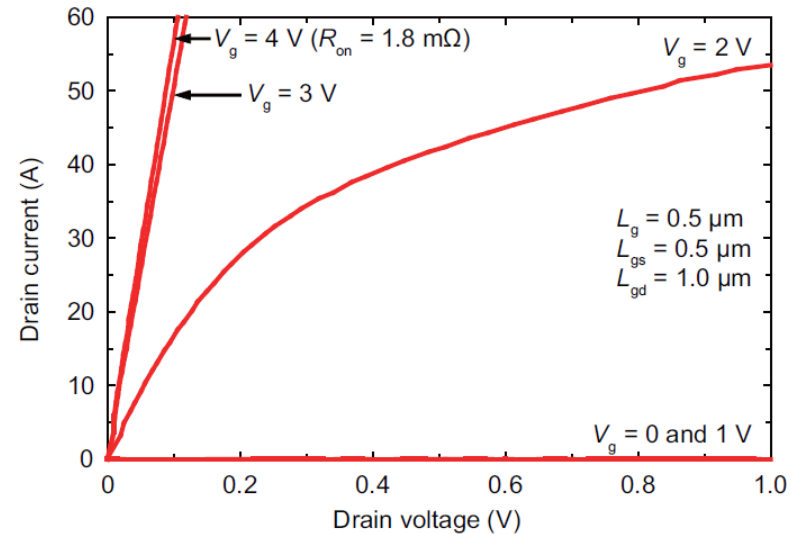
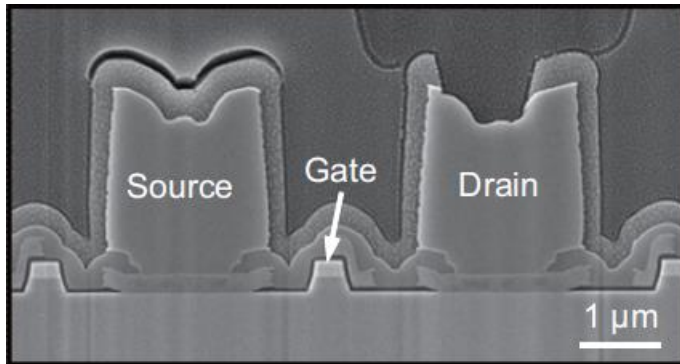
- Increasing frequency greatly helps to reduce the system size.
- Low RonQg power device and low parasitic inductance are key factors.

Advantage by increasing frequency



30V-class normally-off GaN-GITs

- RonQg of developed 30V GaN-GIT is reached to 19.1mΩnC*1.
-> 36% smaller than that of reported Si-MOSFET*2.



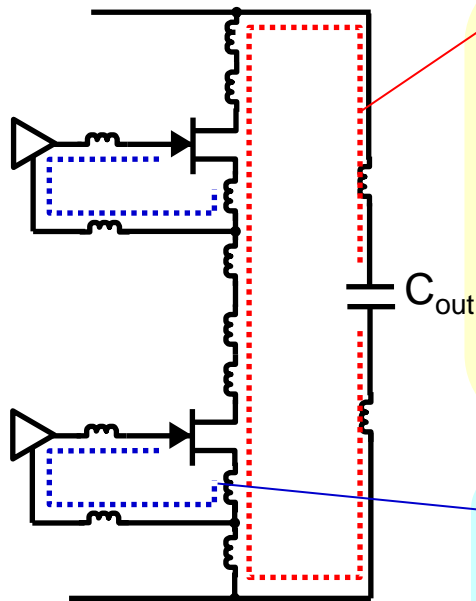
R_{on} (mΩ)	Q_g (nC)	$R_{on} Q_g$ (mΩnC)	Breakdown voltage (V)
1.8	10.6	19.1	30

*1 H. Umeda, et al., PCIM2014

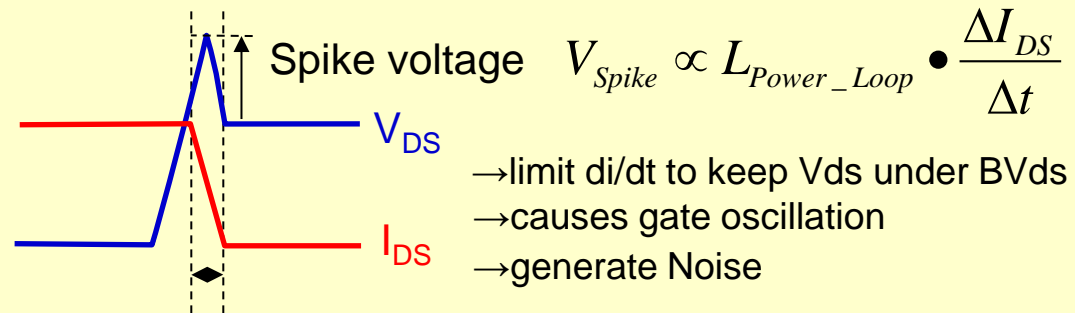
*2 S. Xu, et al., International Electron Devices Meeting (IEDM) Technical Digests, 145(2009)

Impact of the parasitic inductance

- Parasitic inductance on power loop ($L_{\text{Power_Loop}}$) increase the spike voltage
→ It limits di/dt and causes gate oscillation, increase noise.
- Parasitic inductance on gate loop ($L_{\text{Gate_Loop}}$) increase the gate charging time.



Parasitic inductance on Power Loop $L_{\text{Power_Loop}}$



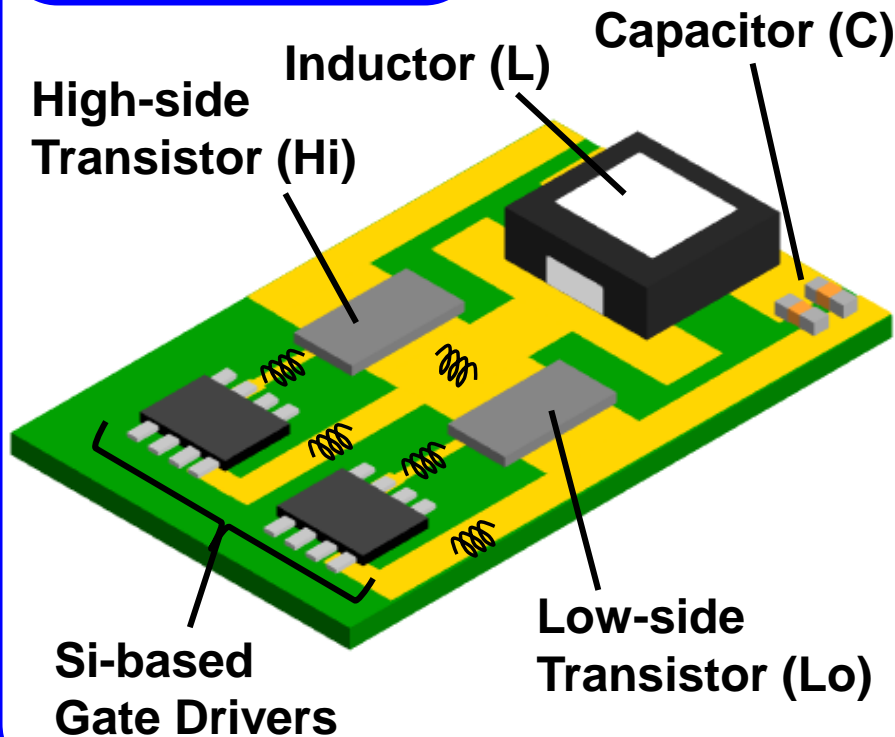
Parasitic inductance on Gate Loop $L_{\text{Gate_Loop}}$

→ Reduction of $L_{\text{Gate_Loop}}$ also effectively increase gate charging speed

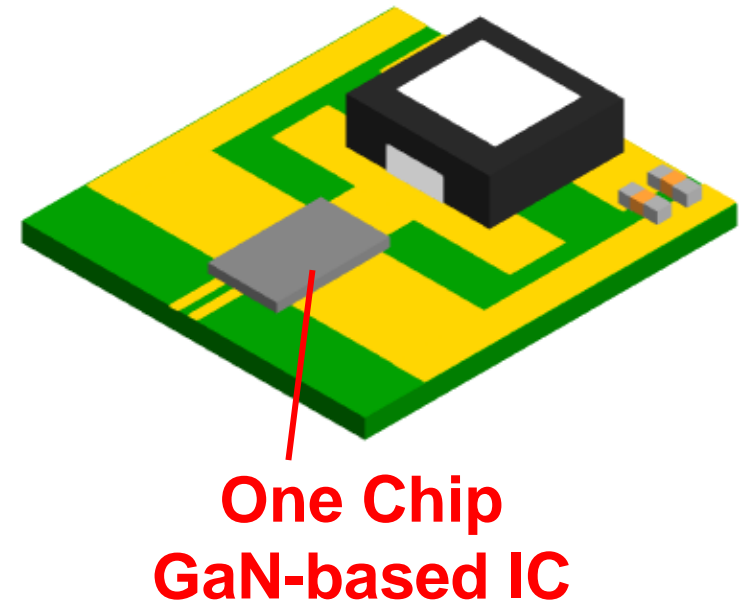
This Work : GaN-based IC with gate driver

- GaN transistors and GaN gate drivers are integrated to a compact chip

Conventional



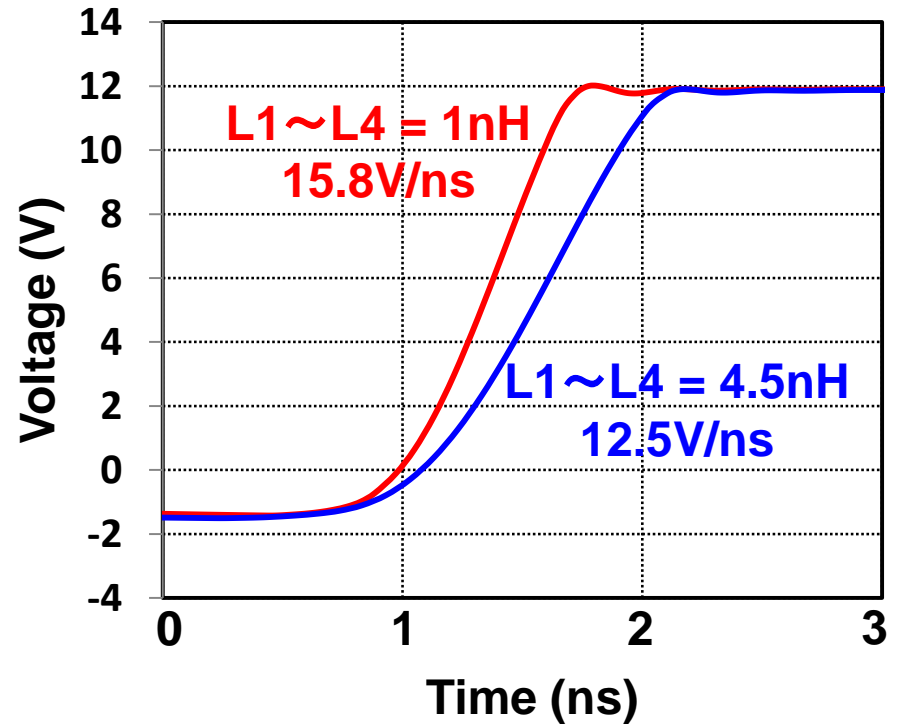
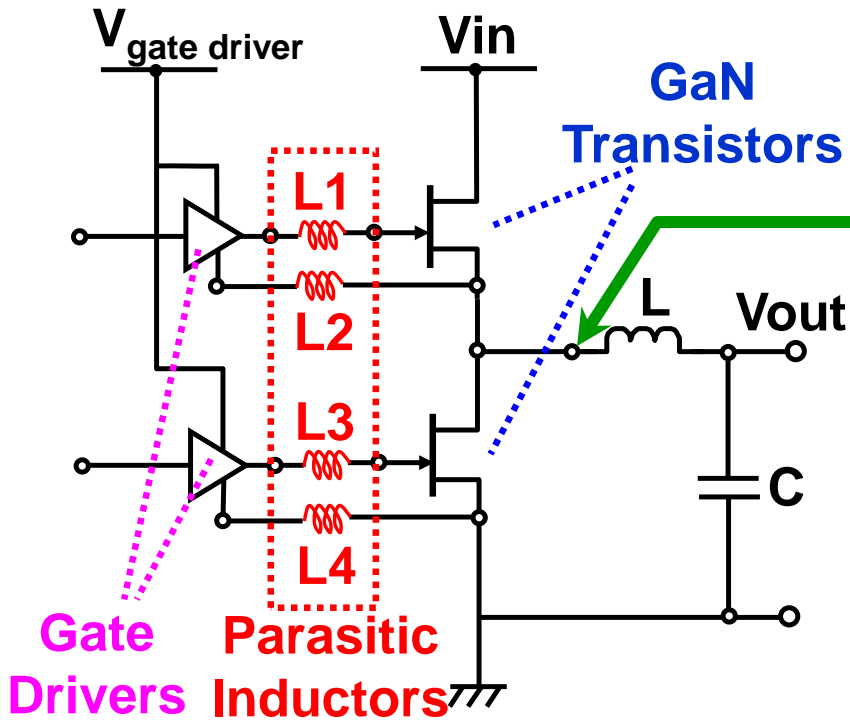
This Work



Impact of Integration : Small Parasitic Inductances

- Switching speed is increased by reduction of parasitic inductances

Simulated turn-on switching waveform

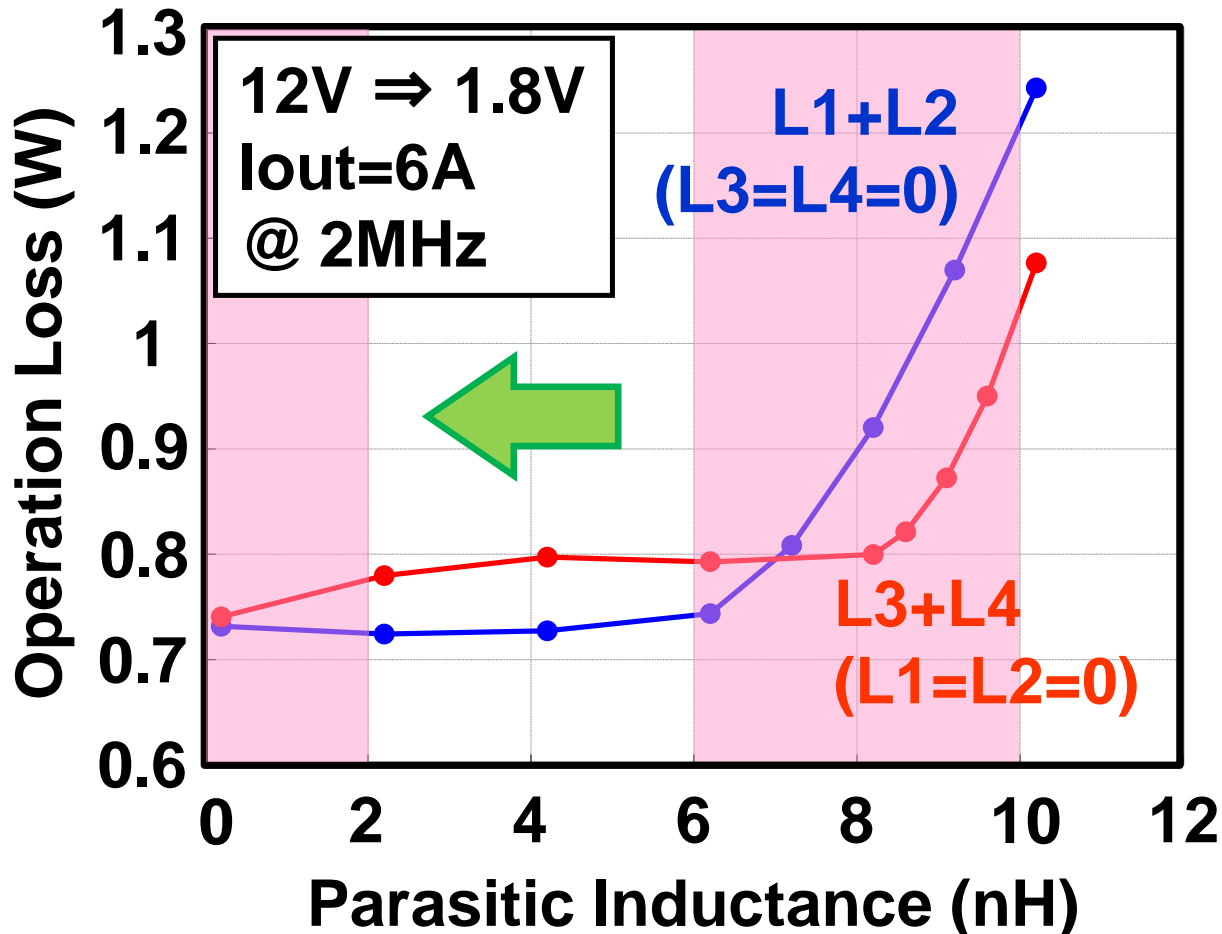


12V \Rightarrow 1.8V $I_{out} = 6A$
2MHz operation

Impact of Integration : Small Parasitic Inductances

- Operation loss is reduced by the reduction of parasitic inductances.

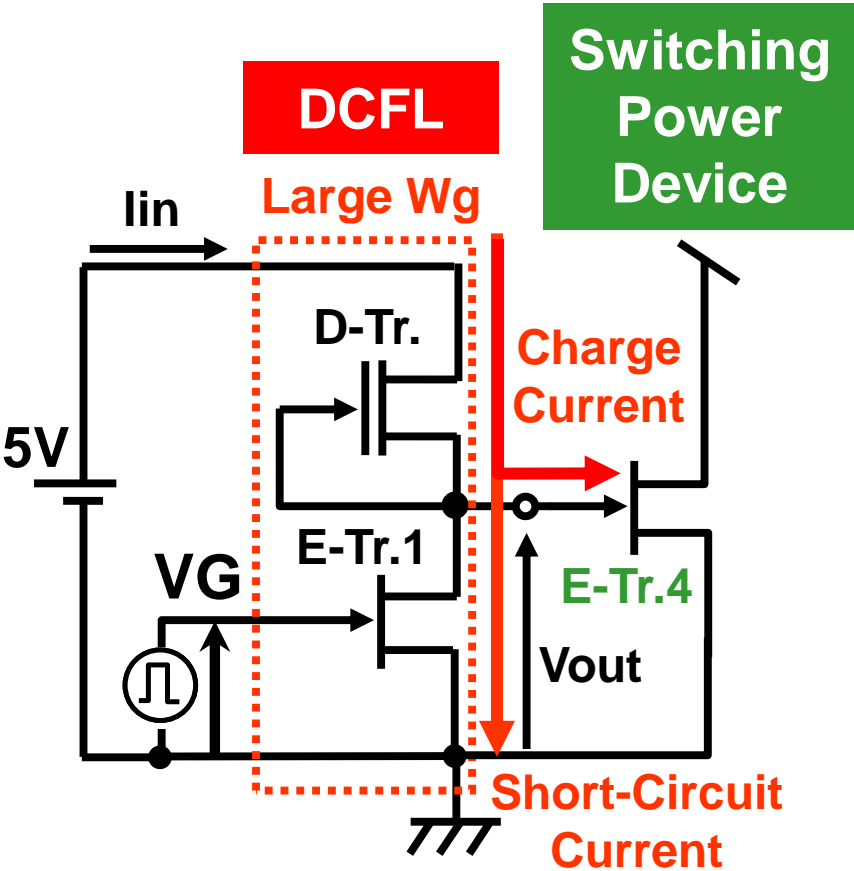
Simulated operation loss



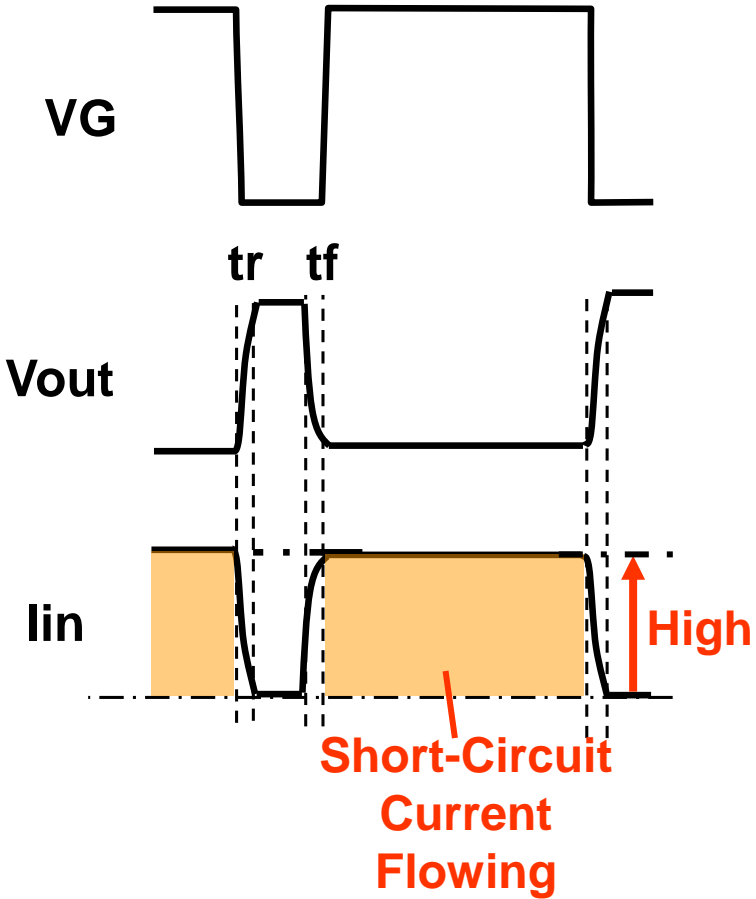
GaN Gate Driver : DCFL (Direct Coupled FET Logic)

- High power consumption in GaN gate driver of DCFL.

Circuit Design



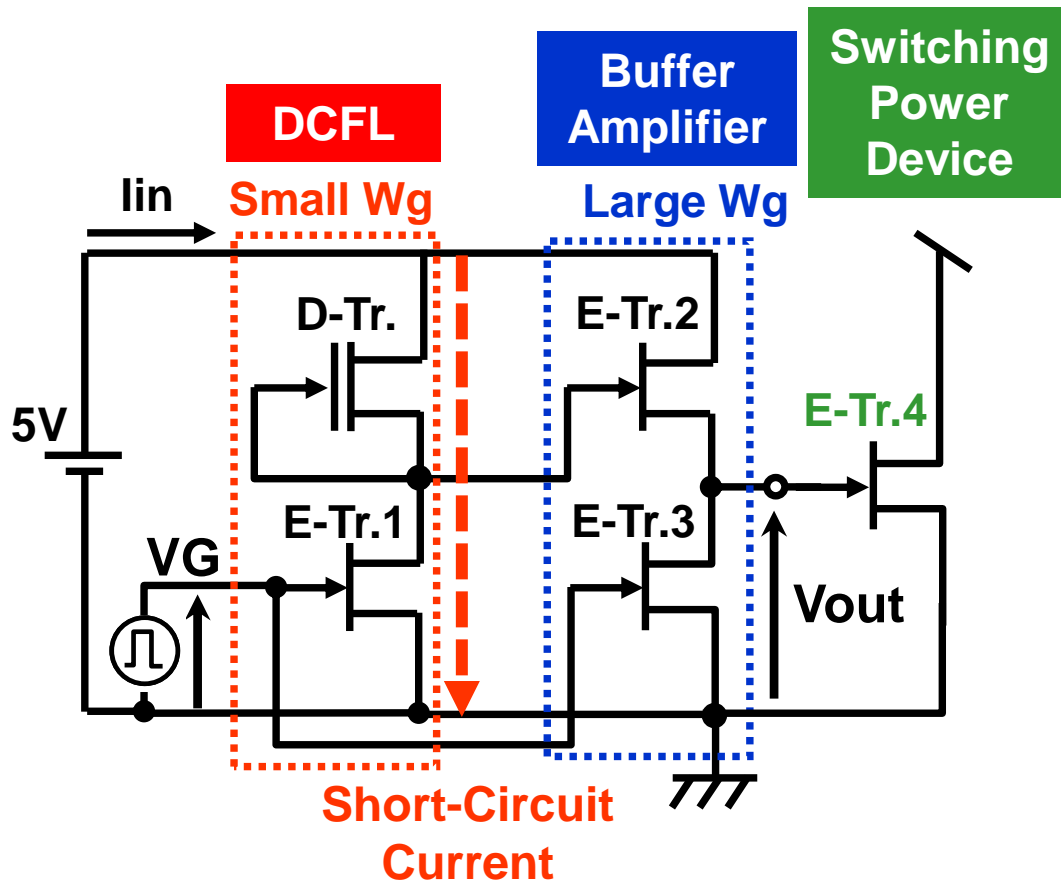
Time Chart



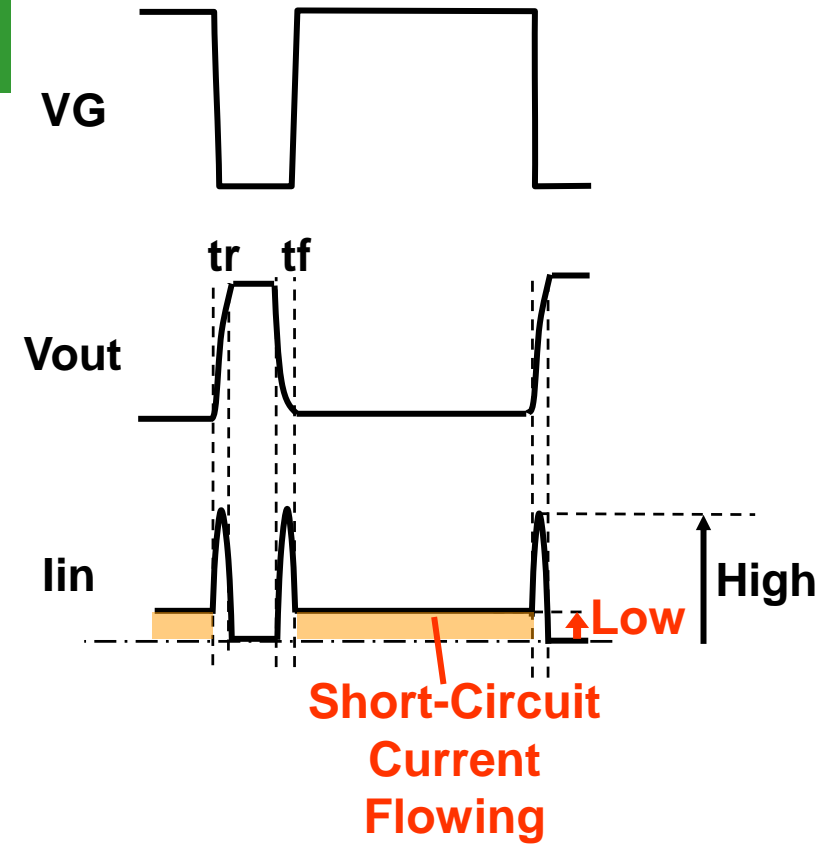
GaN Gate Driver : DCFL with Buffer Amplifier

- Low power consumption in GaN gate driver by buffer amplifier.

Circuit Design



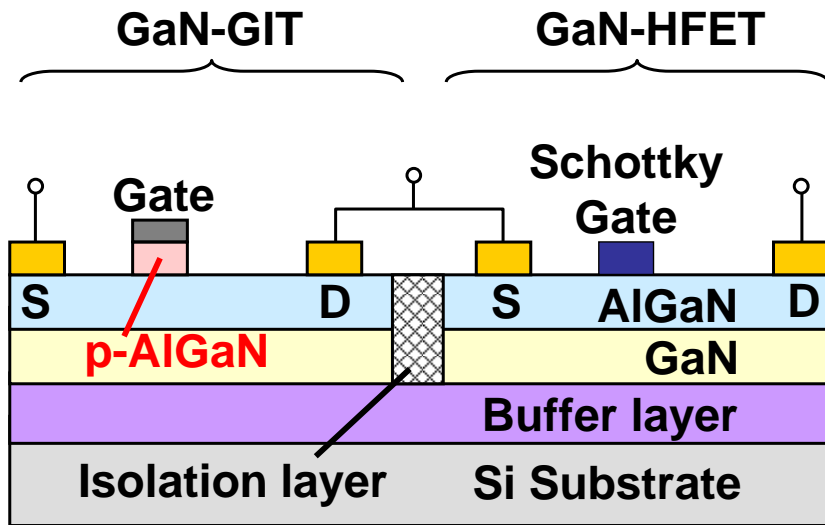
Time Chart



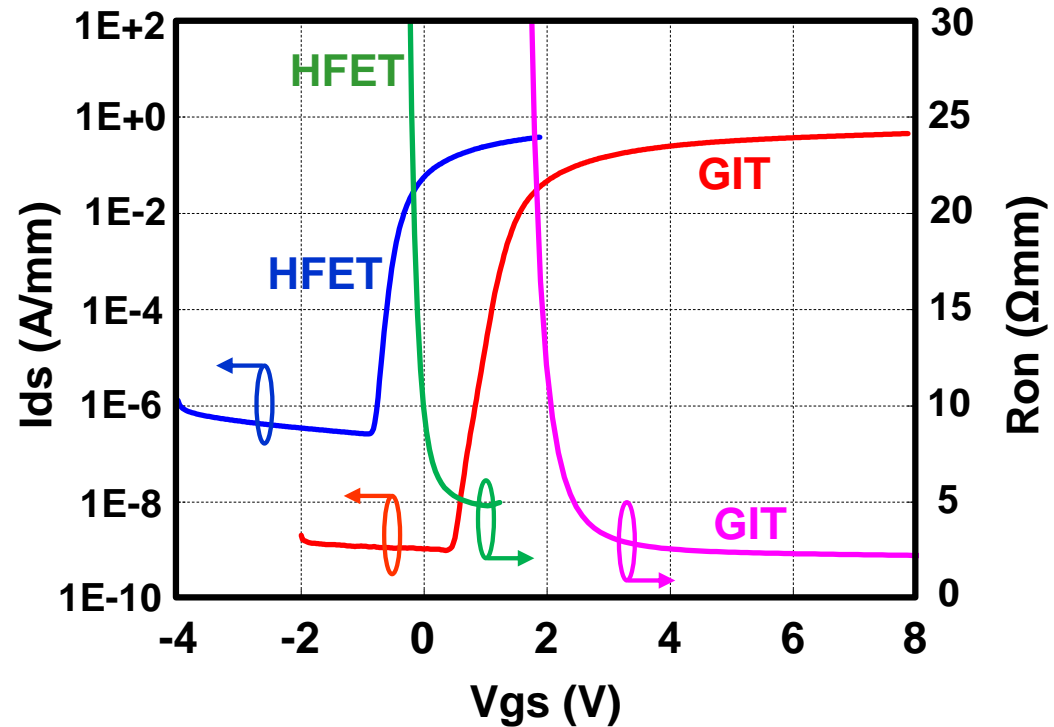
GaN Device Structure and Characteristics

- D-mode HFET and E-mode GIT are monolithically fabricated.

Device Structure

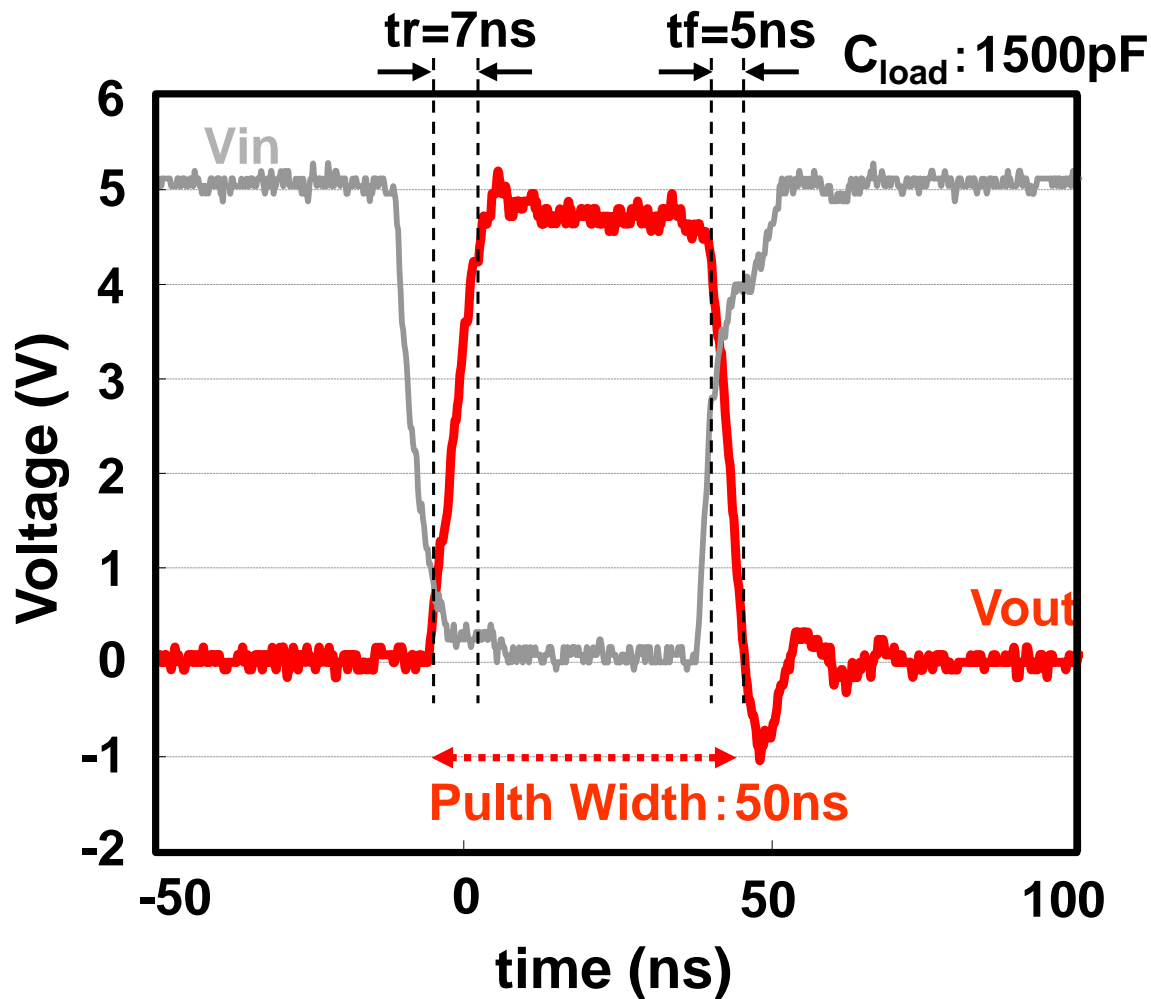


Device Characteristics



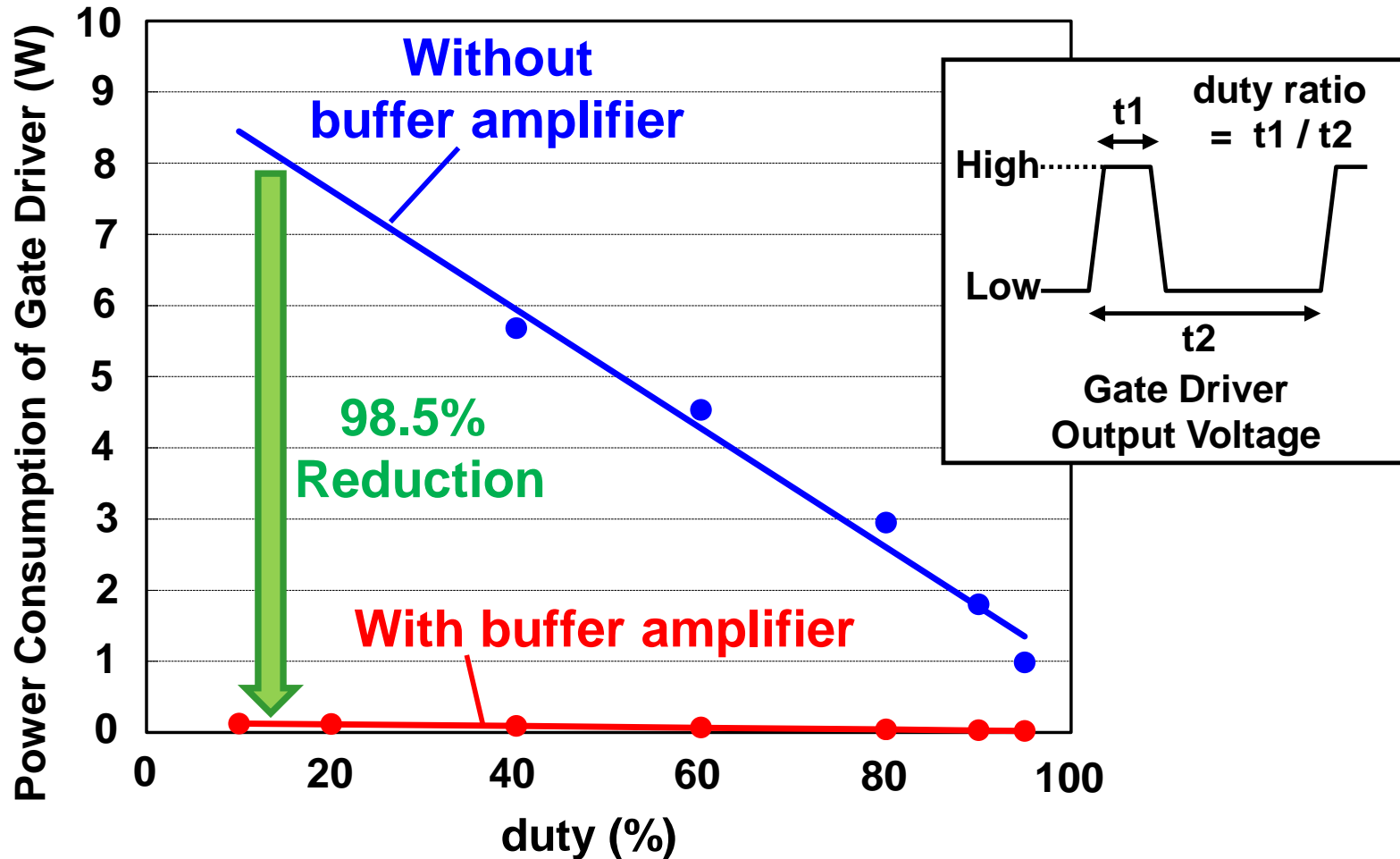
Operation Characteristics of GaN Gate Driver

- GaN gate driver is about 40% faster than Si gate driver.



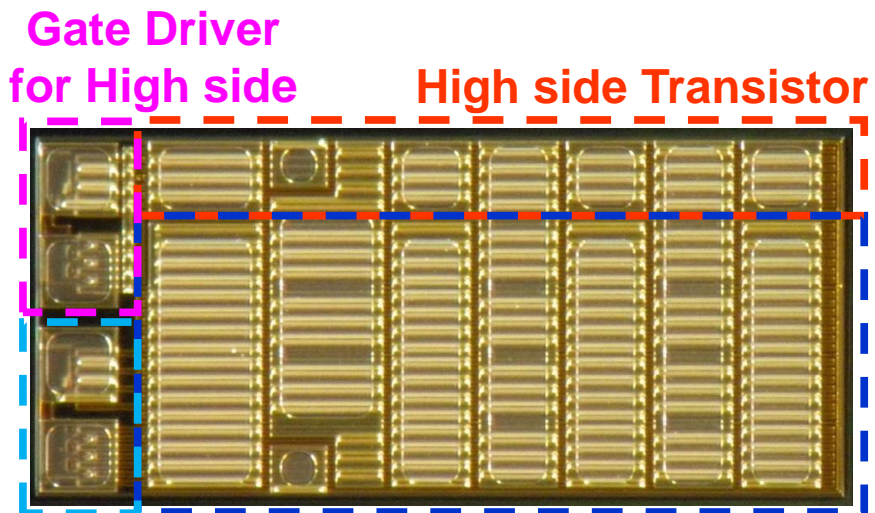
Low Consumption of GaN Gate Driver

- Power consumption is reduced about 98.5% by using GaN DCFL with buffer amplifier.



GaN-based DC-DC Converter IC

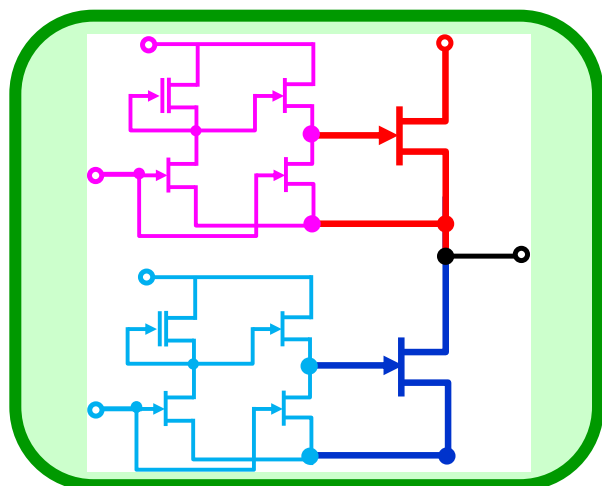
Chip photograph



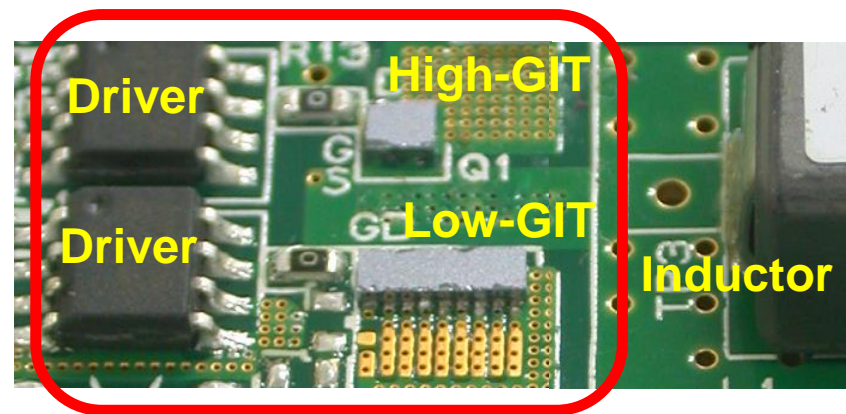
Gate Driver for High side High side Transistor
Gate Driver for Low side Low side Transistor

1mm

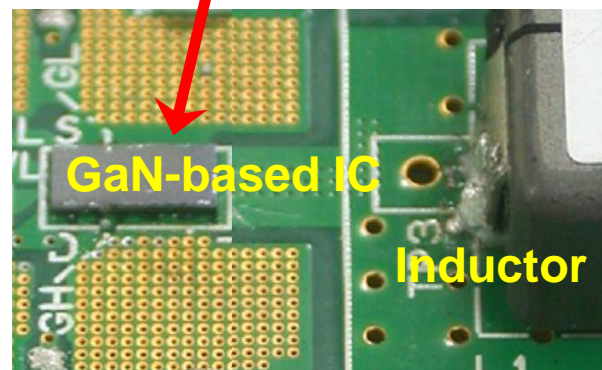
Circuit diagram



Module layout with GaN-based IC



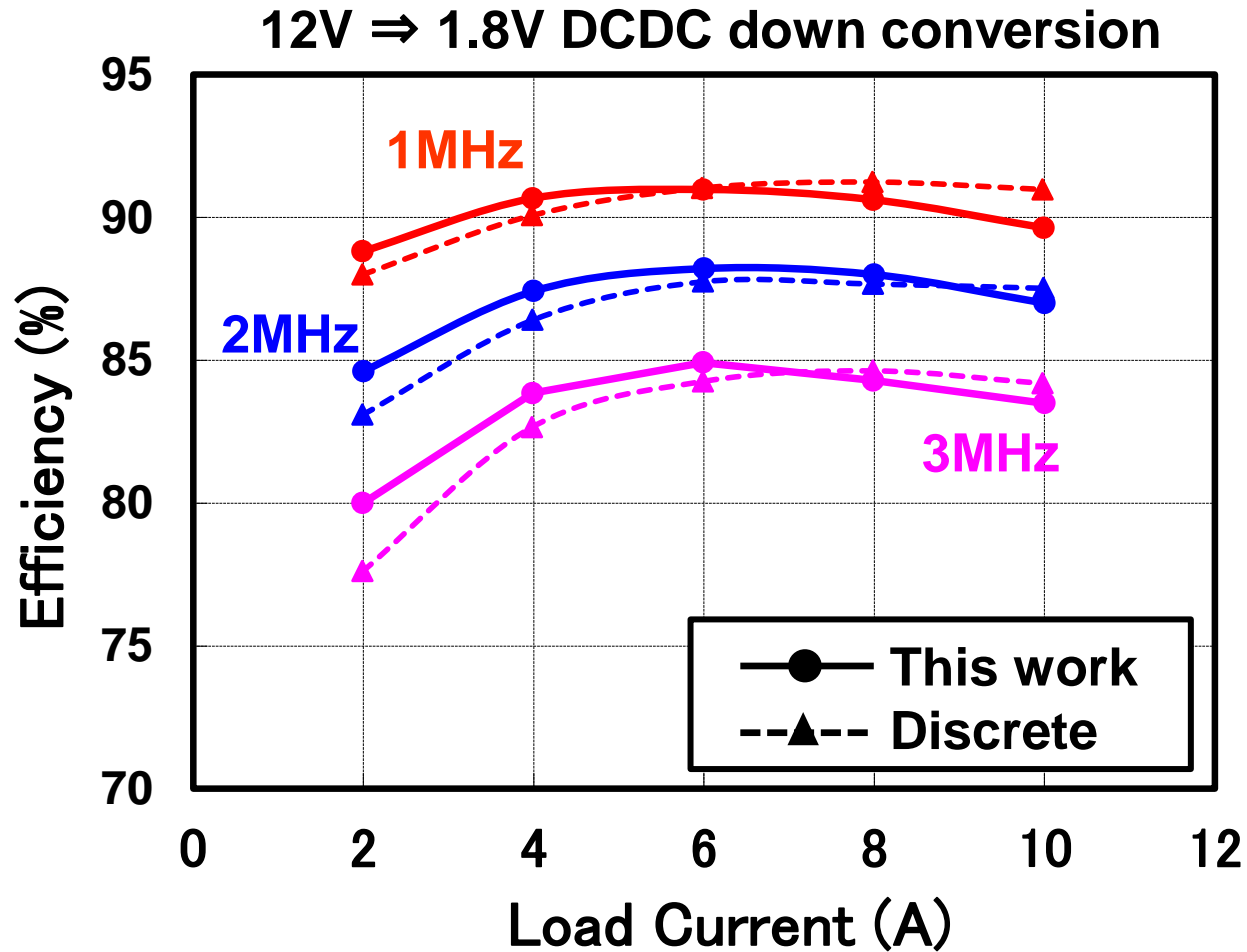
Integration



- Compact chip size is 5.1mm x 2.3mm
- GaN-based IC reduces the system size

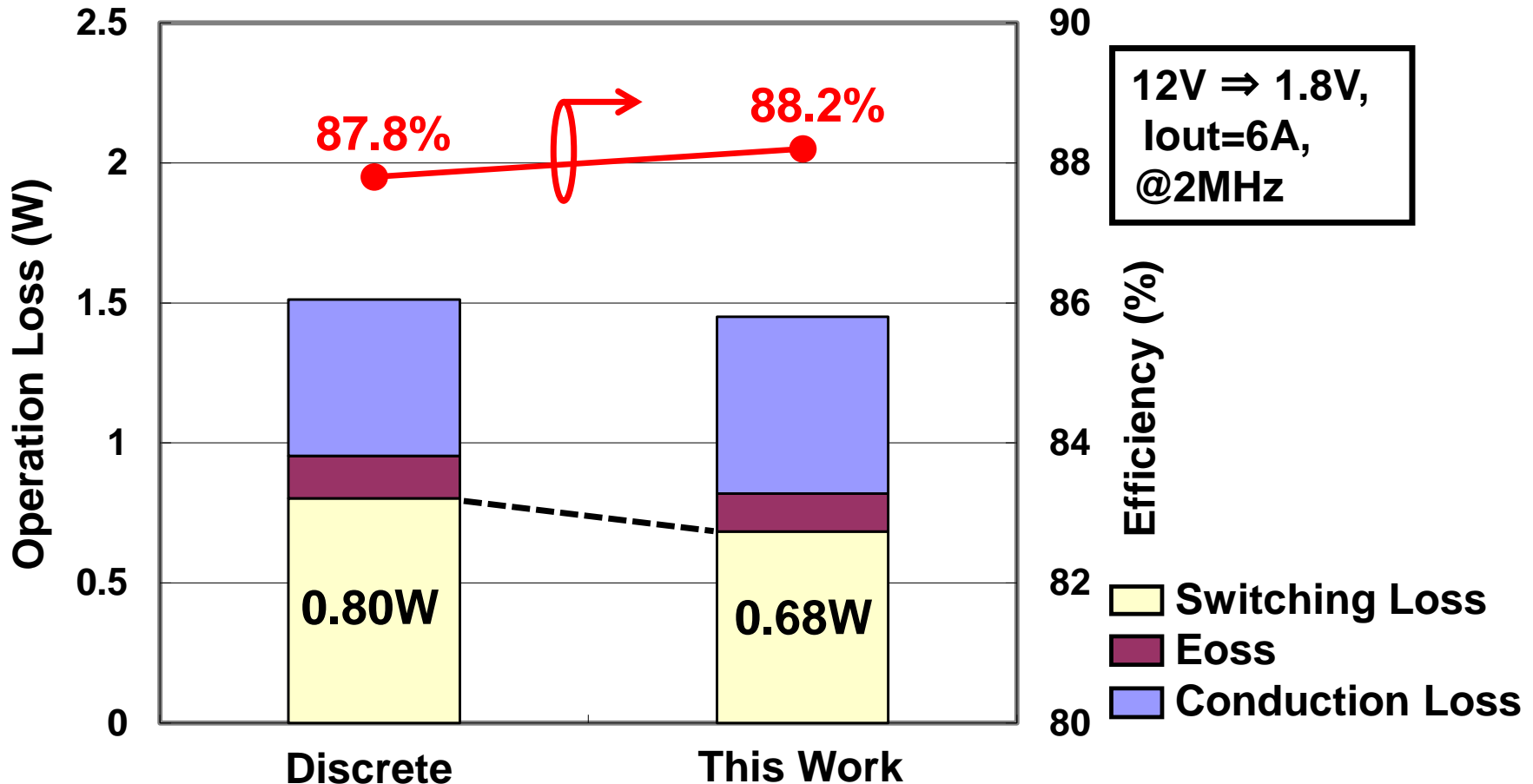
Operating Efficiencies of DC-DC Converter

- Peak efficiency of 88.2% is achieved with 12V - 1.8V DC-DC conversion at 2MHz



Analyzed operating loss of GaN-based IC

- Switching loss have been reduced 15% by using GaN-based DC-DC converter IC.



Compact GaN-based DC-DC Converter IC with High Speed Gate Drivers for Highly Efficient DC-DC Converters

- **GaN Gate Driver** DCFL with buffer amplifier
Monolithically fabrication of HFET and GIT
High speed switching ($t_r + t_f = 12\text{ns}$)
- **GaN-based IC** 5.1mm X 2.3mm Compact chip size
Peak Efficiency (12V-1.8V) : 88.2% @ 2MHz

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